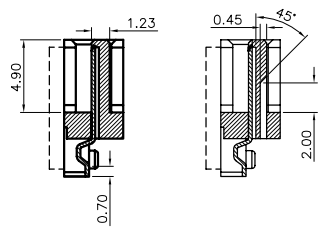
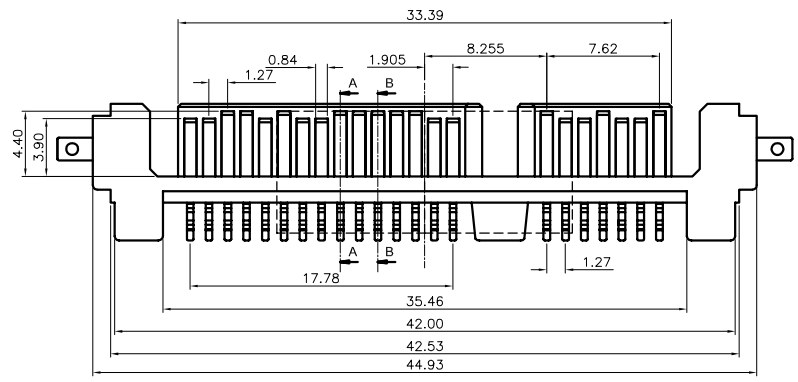
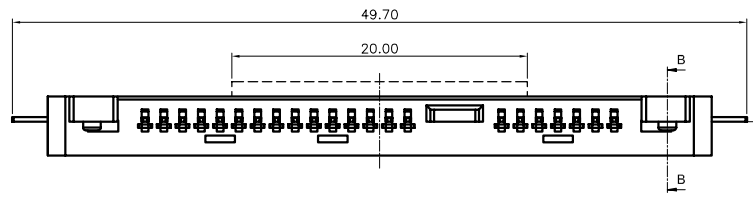


RECOMMENDED P.C. B LAYOUT  
THICKNESS=1.0mm



SECTION A-A SECTION B-B



SECTION B-B

NOTE:

- MATERIAL:  
HOUSING:HIGH TEMPERATURE THERMOPLASTIC,UL94V-0  
COVER:HIGH TEMPERATURE THERMOPLASTIC,UL94V-0  
TERMINAL:COPPER ALLOY,THICKNESS = 0.25 mm  
FORLOCK:COPPER ALLOY,THICKNESS = 0.30 mm
- PLATING:  
CONTACT:GOLD OVER 50u" MIN NICKEL UNDERPLATE  
SOLDER TAIL:75u"MIN TIN 50u" MIN NICKEL UNDERPLATE  
GOLD SPECIFICATION:SEE TABLE,
- ELECTRONICAL SPECIFICATION:  
CURRENT RATING:1.5 AMPERE PER CONTACT  
CONTACT RESISTANCE:30 MILLIOHMS MAX.  
INSULATION RESISTANCE:1000 MEGOHMS MIN.  
DIELECTRIC WITHSTANDING VOLTAGE:500 VDC.  
OPERATING TEMPERATURE:-40C~+85C

RoHS Compliant

TOLERANCES ARE



煜倫股份有限公司

www.morethanall.com

DRAWING BY CY

CHECKED BY GENIUS

UNIT / mm SCALE 1 : 1

DATE

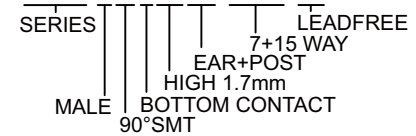
SIZE A4 PPROJECTION

X, ±  
.X ± 0.30  
.XX ± 0.25  
.XXX ±  
ANG ± 3°

照片框

ORDER INFORMATION

SATA-PWB17EP-7+15-LF



DESCRIPTION: SATA 22P 公頭沉板式